
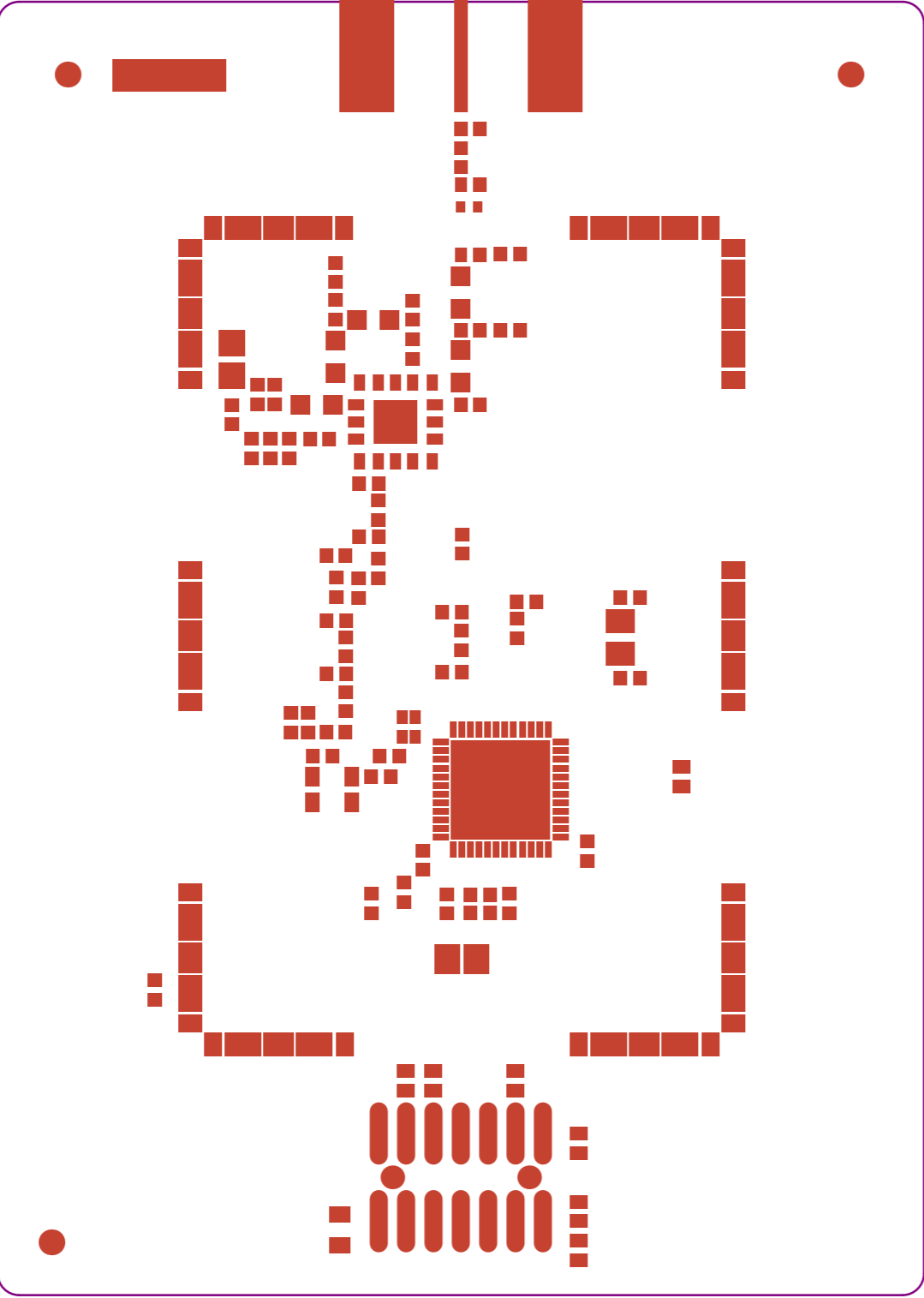

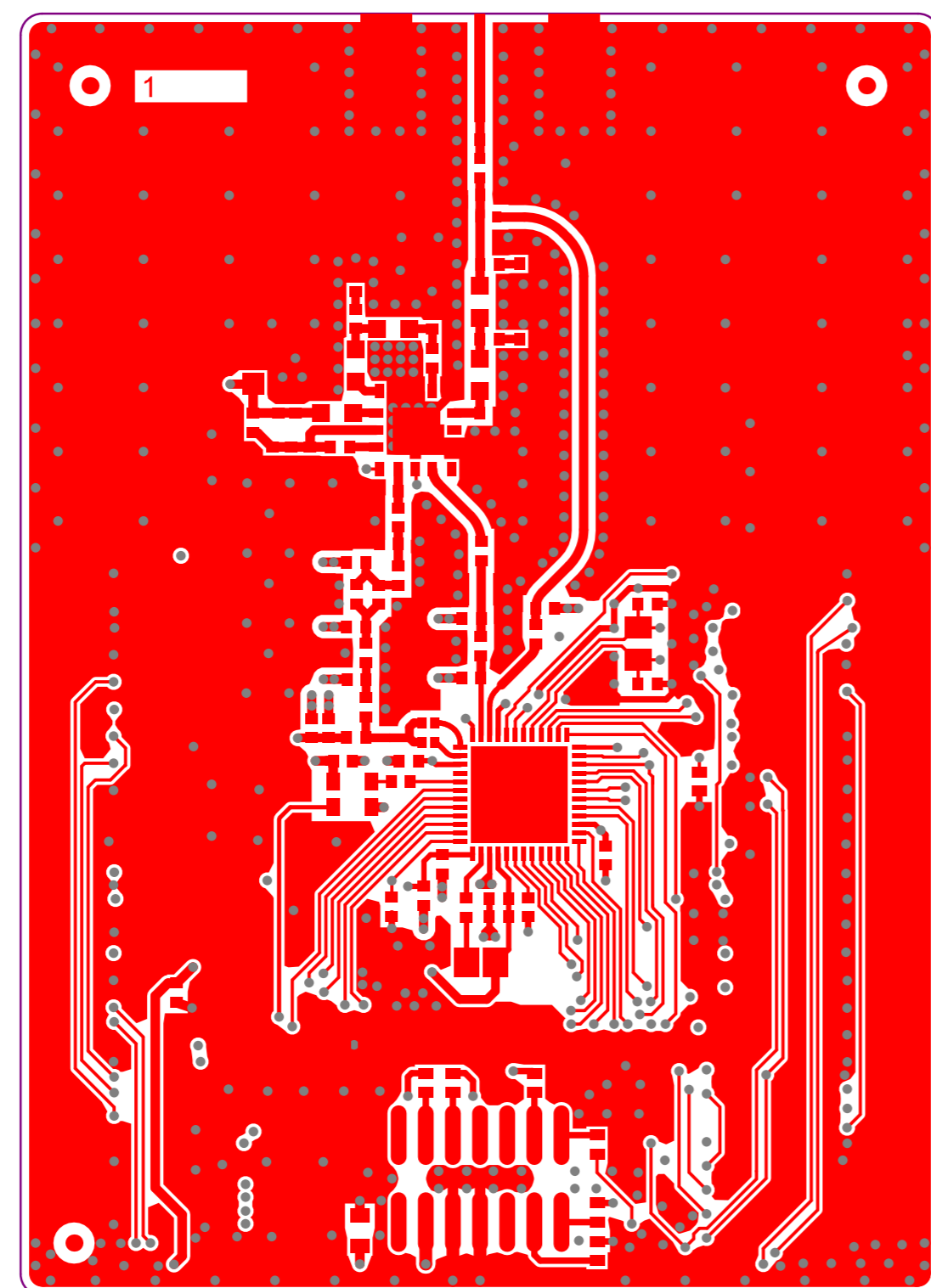



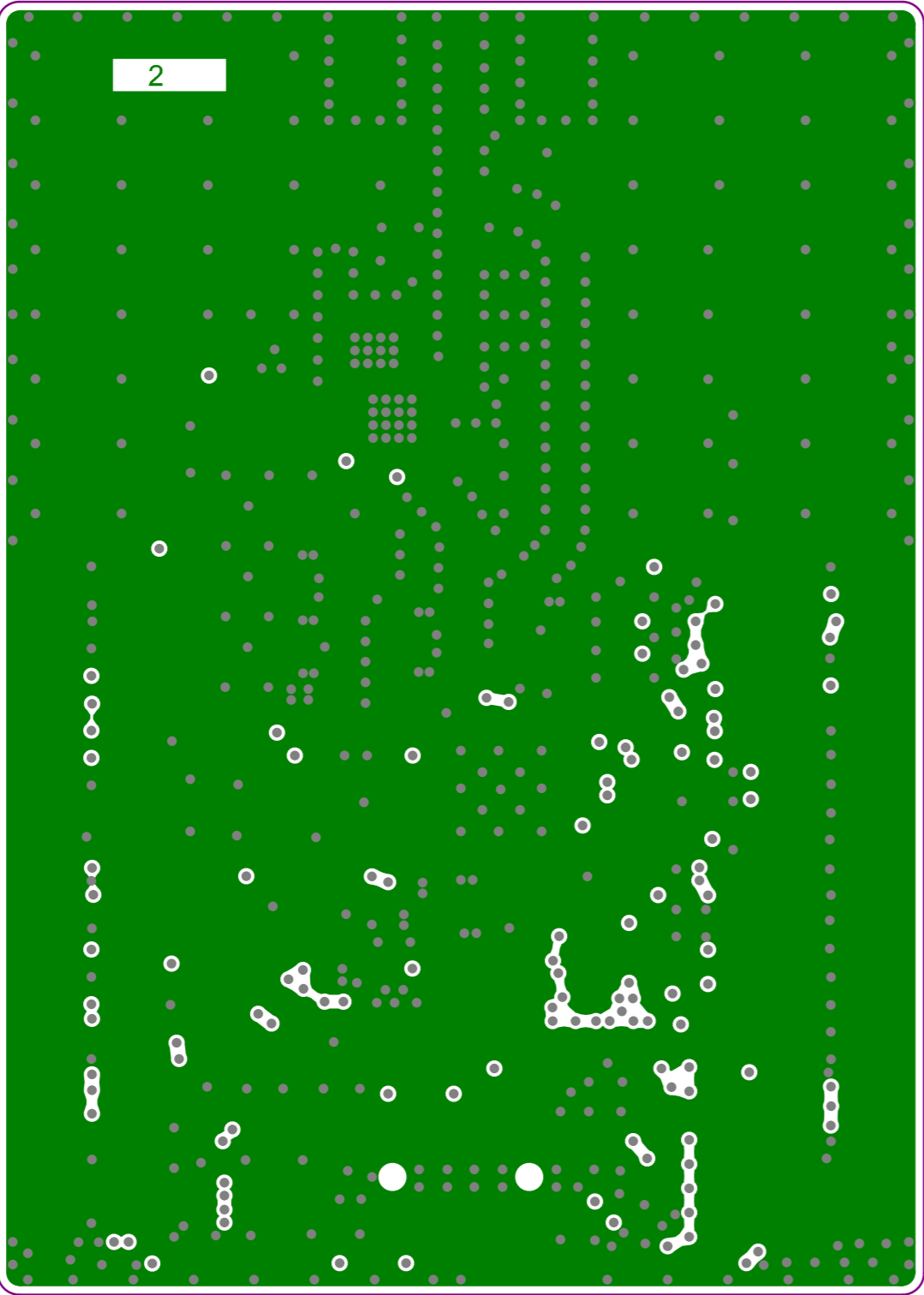
Project: STM32WL3 - QFN48 - 4-Layers - External PA		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB2158	
Date: 12/02/2024	Rev: A	




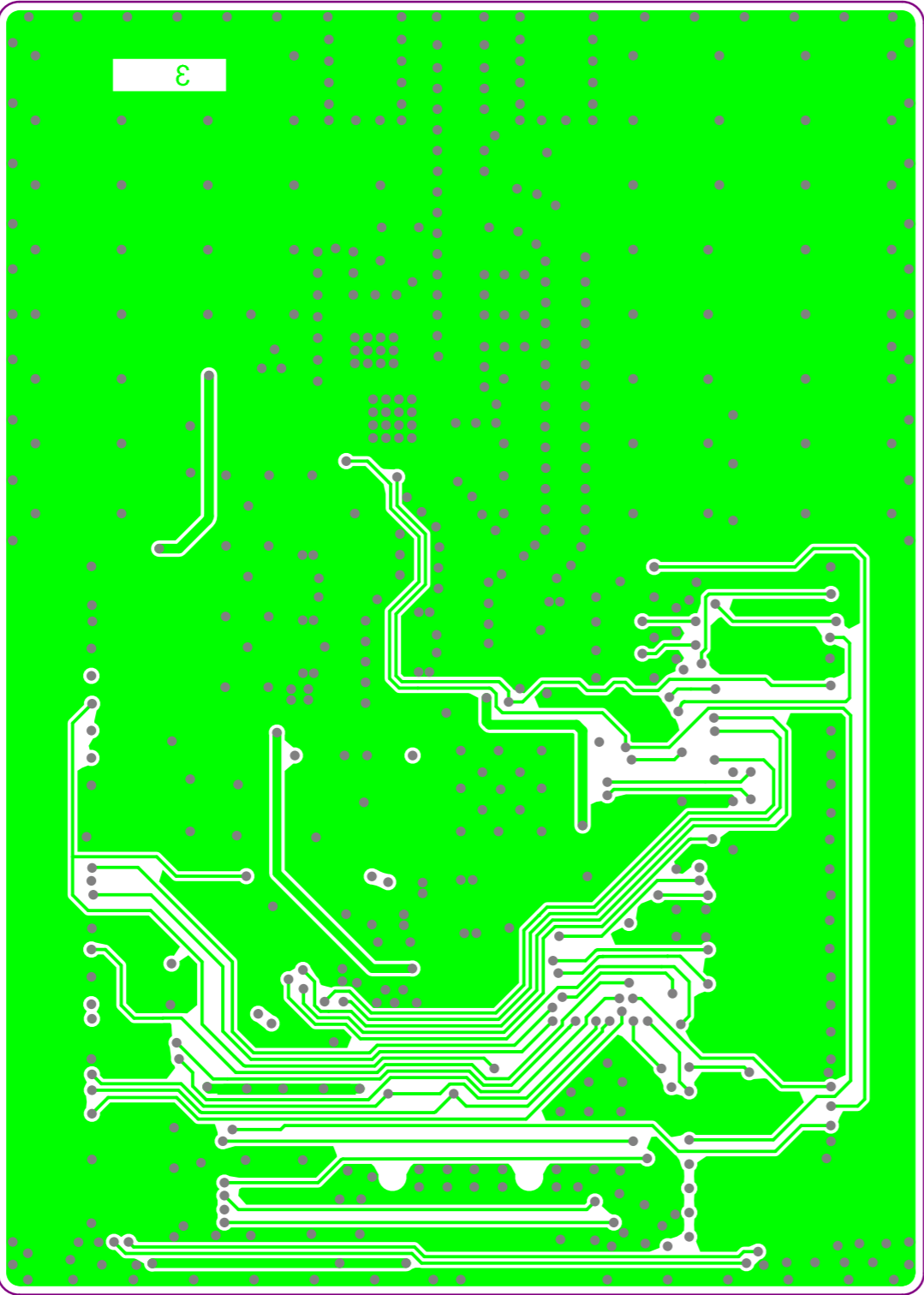
Project: STM32WL3 - QFN48 - 4-Layers - External PA		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB2158	
Date: 12/02/2024	Rev: A	




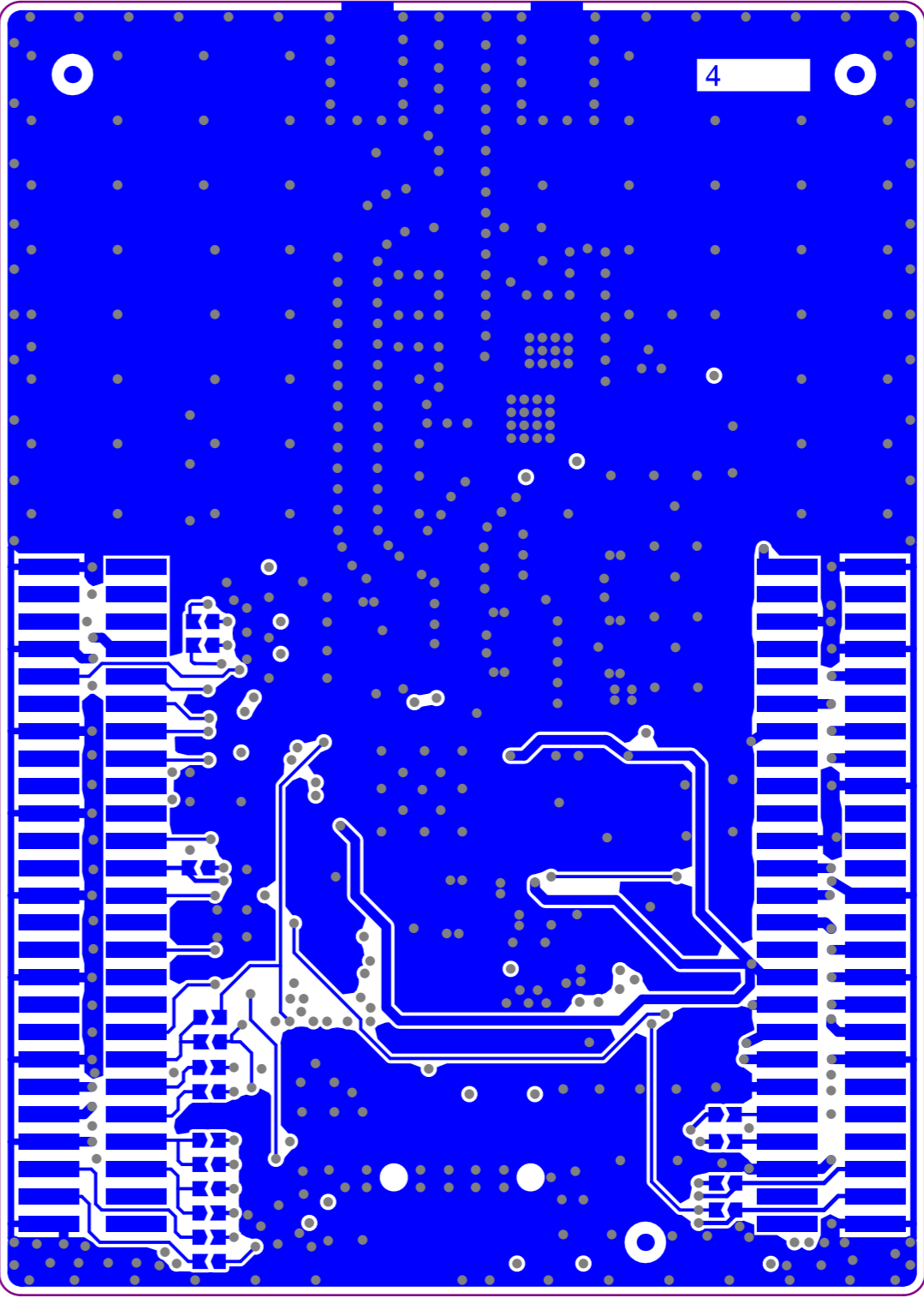
Project: STM32WL3 - QFN48 - 4-Layers - External PA		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB2158	
Date: 12/02/2024	Rev: A	




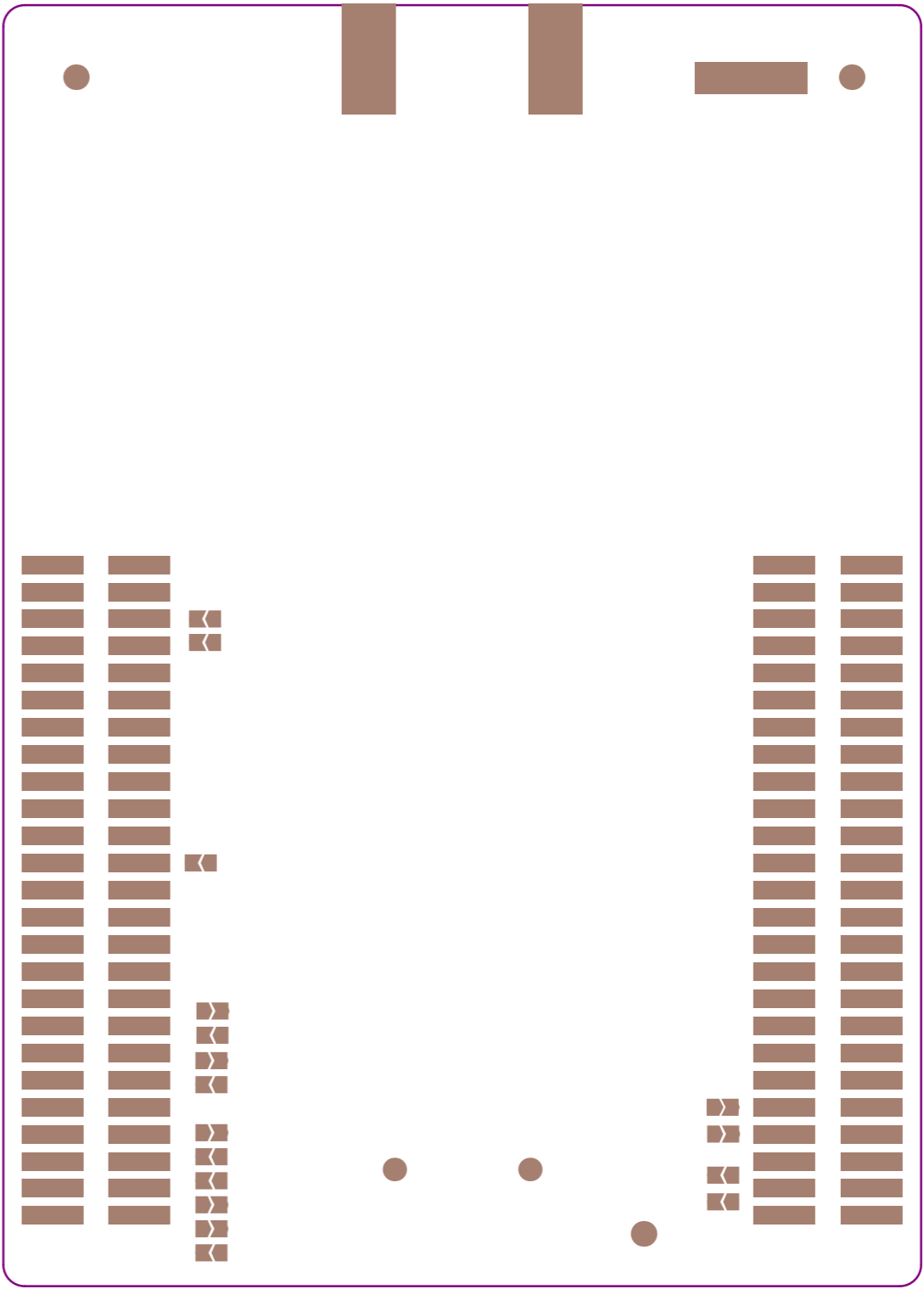
Project: STM32WL3 - QFN48 - 4-Layers - External PA		
Layer: Signal Layer 1	Gerber: .G1	
Variant: [No Variations]	Ref: MB2158	
Date: 12/02/2024	Rev: A	




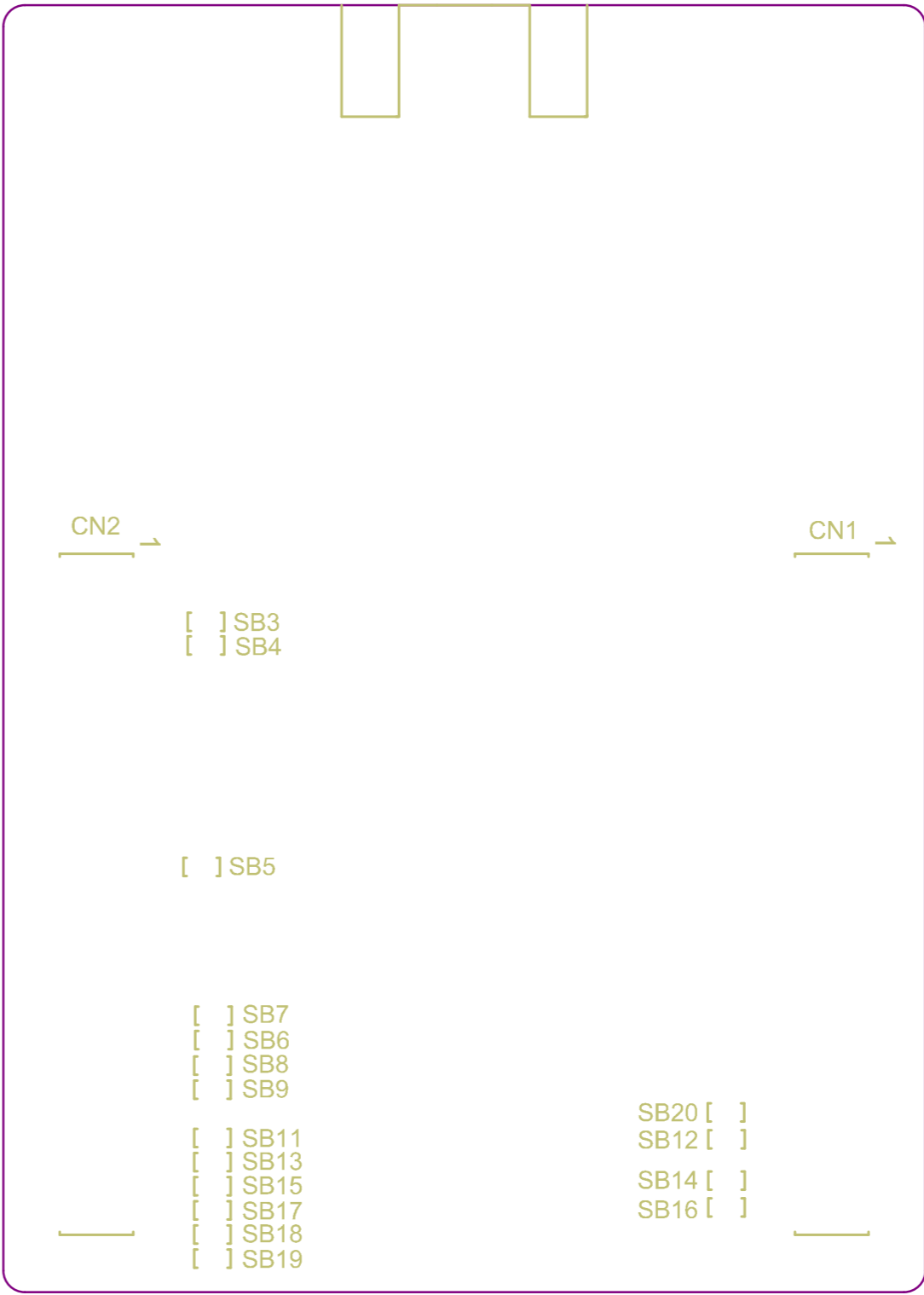
Project: STM32WL3 - QFN48 - 4-Layers - External PA		
Layer: Signal Layer 2	Gerber: .G2	
Variant: [No Variations]	Ref: MB2158	
Date: 12/02/2024	Rev: A	




Project: STM32WL3 - QFN48 - 4-Layers - External PA		
Layer: Bottom Layer	Gerber: .GBL	
Variant: [No Variations]	Ref: MB2158	
Date: 12/02/2024	Rev: A	



Project: STM32WL3 - QFN48 - 4-Layers - External PA		
Layer: Bottom Solder	Gerber:.GBS	
Variant: [No Variations]	Ref: MB2158	
Date: 12/02/2024	Rev: A	



Project: STM32WL3 - QFN48 - 4-Layers - External PA		
Layer: Bottom Overlay	Gerber: .GBO	
Variant: [No Variations]	Ref: MB2158	
Date: 12/02/2024	Rev: A	

PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☐ TG-170

☒ TG-150

☐ TG-140

B. MATERIAL FAMILY :

Ventec VT/47

C. SOLDERMASK COLOR :

☐ GREEN

☒ BLUE

☐ RED

☐ BLACK

D. SILKSCREEN COLOR :

☒ WHITE

☐ YELLOW

☐ BLACK

E. SURFACE FINISH :

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

F. IMPEDANCE CONTROL :

☐ NO

☒ YES

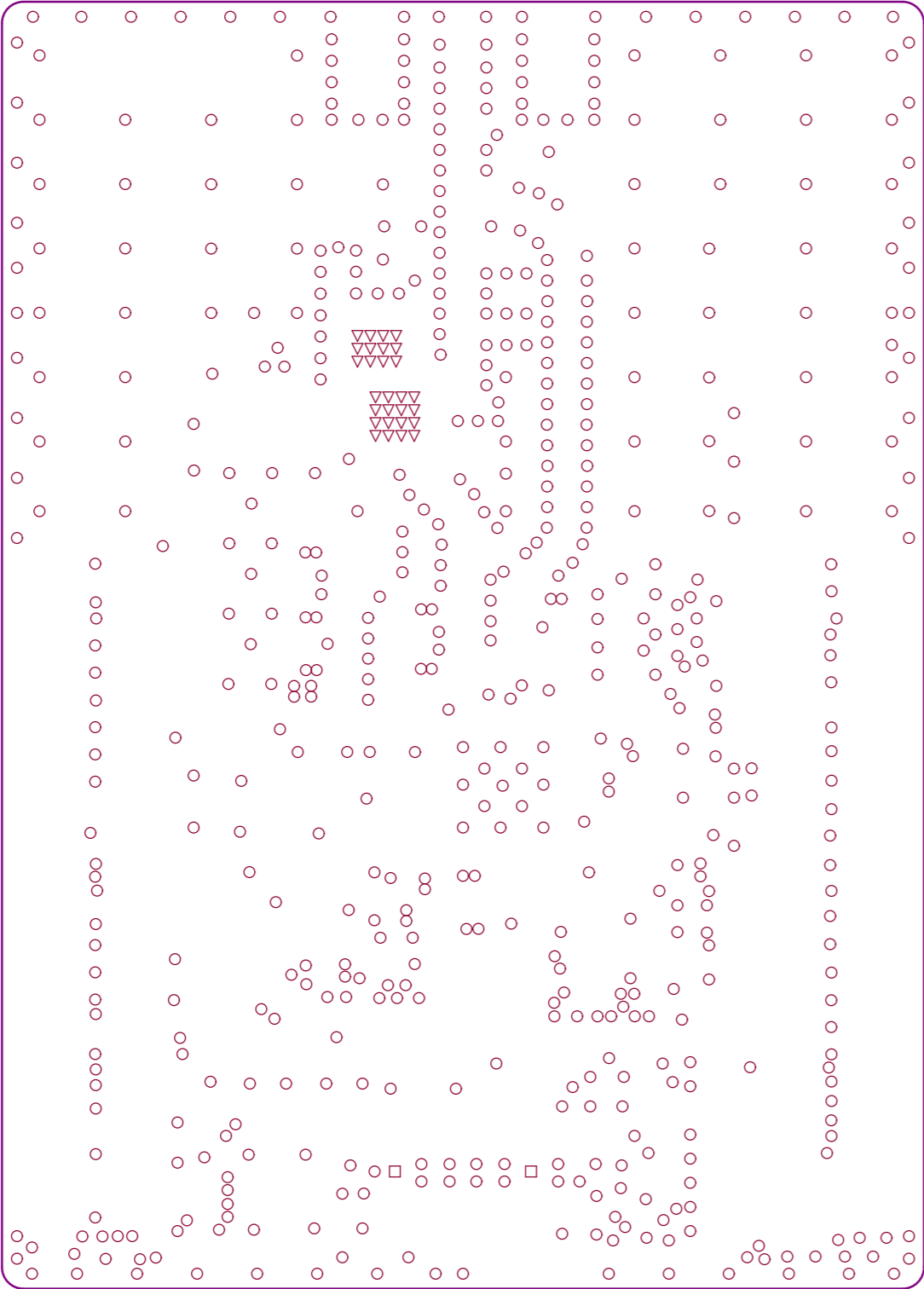
G. THROUGH VIA :

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

H. STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

Layer	Name	Material	Thickness	Constant
	Top Overlay			
	Top Solder	Solder Resist	0.010mm	3.5
1	Top Layer	Copper	0.041mm	
	Dielectric 1	FR4 VT-47	0.254mm	4
2	Signal Layer 1	Copper	0.018mm	
	Dielectric 2	FR4 VT-47	0.914mm	4.3
3	Signal Layer 2	Copper	0.018mm	
	Dielectric 3	FR4 VT-47	0.254mm	4
4	Bottom Layer	Copper	0.041mm	
	Bottom Solder	Solder Resist	0.010mm	3.5
	Bottom Overlay			



PCB : TYPE 3


ASPECT-RATIO, AXE Z :

6 :1 à 8 :1
LEVEL "B"

MINIMUN PARAMETERS

DEFAULT
TRACKS : 0.150mm
GAPS : 0.150mm

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Hole Length
○	593	0.20mm (7.87mil)	PTH	Round	Top Layer - Bottom Layer	Via	-
▽	28	0.30mm (11.81mil)	PTH	Round	Top Layer - Bottom Layer	Via	-
□	2	1.00mm (39.37mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-
	623 Total						

Project: STM32WL3 - QFN48 - 4-Layers - External PA		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	Ref: MB2158	
Date: 12/02/2024	Rev: A	